

THERMOSETTING FLUORINATED DIELECTRICS AND MULTILAYER
CIRCUIT BOARDS

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ABSTRACT OF THE DISCLOSURE

10 A dielectric film is obtained by heat curing a
thermally curable fluorinated o-aminophenol polymer or
oligomer based on an o-aminophenol compound and an
aromatic dicarboxylic acid compound, at least one of
which is mono- or poly-fluorinated, and having
thermosetting groups at both ends that undergo cross-
15 linking reaction upon thermal treatment. The dielectric
film is employed in multilayer circuit boards.

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